

Table 9: DC Parameters (Die)

Symbol	Parameters	Min ⁽²⁾	Typ ⁽¹⁾	Max ⁽²⁾	Units	Conditions
A _{ARP}	ANA IN to SP +/- Gain		22		dB	
R _{AGC}	AGC Output Resistance		5		K Ω	
I _{PREH}	Preamp Out Source		-2		mA	@ V _{OUT} = 1.0 V
I _{PREL}	Preamp In Sink		0.5		mA	@ V _{OUT} = 2.0 V

1. Typical values @ T_A = 25°C and 5.0 V.
2. All Min/Max limits are guaranteed by ISD via electrical testing or characterization. Not all specifications are 100 percent tested.
3. V_{CCA} and V_{CCD} connected together.
4. REC, PLAYL, and PLAYE must be at V_{CCD}.
5. REC, PLAYL, and PLAYE, A6, A7.
6. A0-A5, XCLK.

Table 10: AC Parameters (Die)

Symbol	Characteristic	Min ⁽²⁾	Typ ⁽¹⁾	Max ⁽²⁾	Units	Conditions	
F _S	Sampling Frequency	ISD1110		6.4	KHz	(5)	
		ISD1112		5.3	KHz	(5)	
F _{CF}	Filter Pass Band	ISD1110	2.6		KHz	3 dB Roll-Off Point ⁽³⁾⁽⁶⁾	
		ISD1112	2.2		KHz	3 dB Roll-Off Point ⁽³⁾⁽⁶⁾	
T _{REC}	Record Duration	ISD1110	10		sec		
		ISD1112	12		sec		
T _{PLAY}	Playback Duration	ISD1110	10		sec	(5)	
		ISD1112	12		sec	(5)	
T _{LED1}	RECLED ON Delay		5		μ sec		
T _{LED2}	RECLED OFF Delay	ISD1110	40	48.5	100	msec	
		ISD1112	50	58.3	105	msec	
T _{SET}	A0-A7 Setup Time	300			nsec		
T _{HOLD}	A0-A7 Hold Time	0			nsec		
T _{RPUD}	Record Power-Up Delay	ISD1110	32		msec		
		ISD1112	39		msec		
T _{RPDD}	Record Power-Down Delay	ISD1110	32		msec		
		ISD1112	39		msec		
T _{PPUD}	Play Power-Up Delay	ISD1110	32		msec		
		ISD1112	39		msec		
T _{PPDD}	Play Power-Down Delay	ISD1110	8.1		msec		
		ISD1112	9.7		msec		

Table 10: AC Parameters (Die)

Symbol	Characteristic	Min ⁽²⁾	Typ ⁽¹⁾	Max ⁽²⁾	Units	Conditions
T _{EOM}	EOM Pulse Width		ISD1110	15.625		msec
			ISD1112	18.75		msec
THD	Total Harmonic Distortion		1		%	@ 1 KHz
P _{OUT}	Speaker Output Power		12.2		mW	R _{EXT} = 16 Ω
V _{OUT}	Voltage Across Speaker Pins		1.25	2.5	mVp-p	R _{EXT} = 600 Ω
V _{IN1}	MIC Input Voltage			20	mV	Peak-to-Peak ⁽⁴⁾
V _{IN2}	ANA IN Input Voltage			50	mV	Peak-to-Peak

1. Typical values @ T_A = 25°C and 5.0 V.
2. All Min/Max limits are guaranteed by ISD via electrical testing or characterization. Not all specifications are 100 percent tested.
3. Low-frequency cutoff depends upon value of external capacitors (see Pin Descriptions).
4. With 5.1 KΩ series resistor at ANA IN.
5. Sampling frequency and playback duration will vary as much as ±2.25 percent over the commercial temperature and voltage ranges. All devices will meet the maximum sampling frequency and minimum playback duration parameters. For greater stability, an external clock can be utilized (see Pin Descriptions).
6. Filter specification applies to the antialiasing filter and to the smoothing filter.

TYPICAL PARAMETER VARIATION WITH VOLTAGE AND TEMPERATURE (DIE)

Chart 5: Record Mode Operating Current (I_{CC})

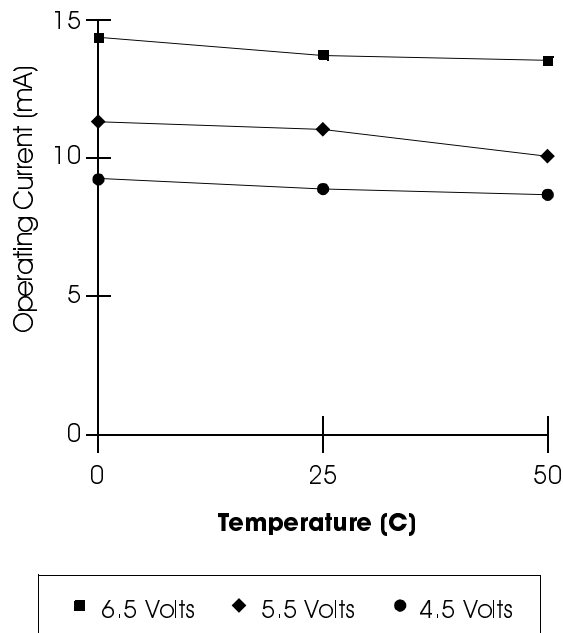


Chart 7: Standby Current (I_{SB})

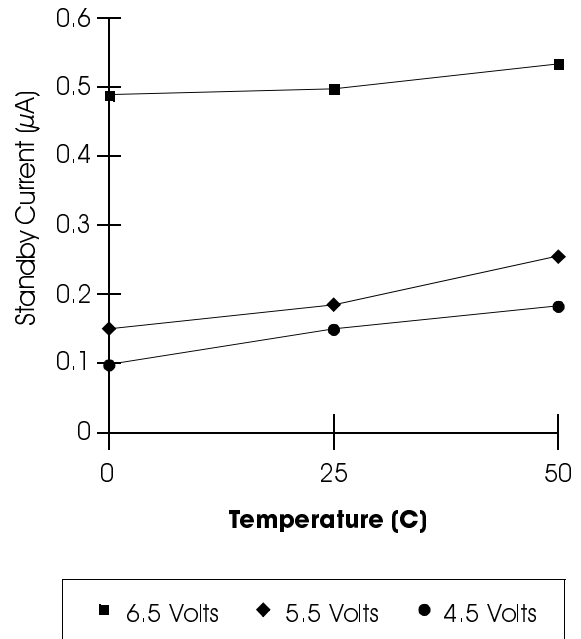


Chart 6: Total Harmonic Distortion

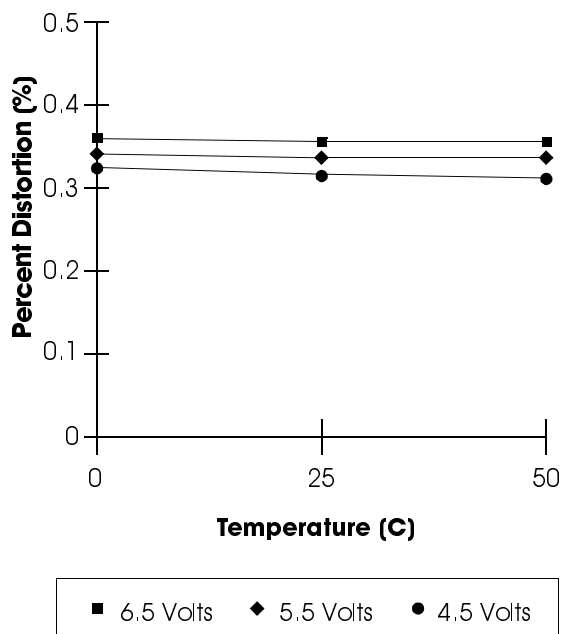


Chart 8: Oscillator Stability

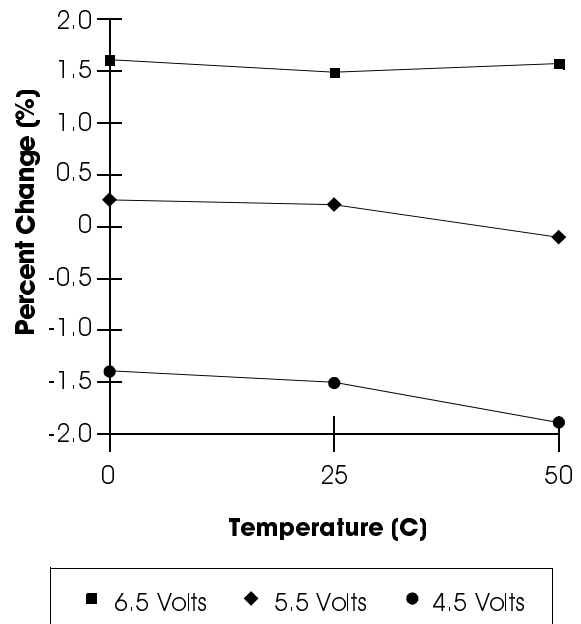
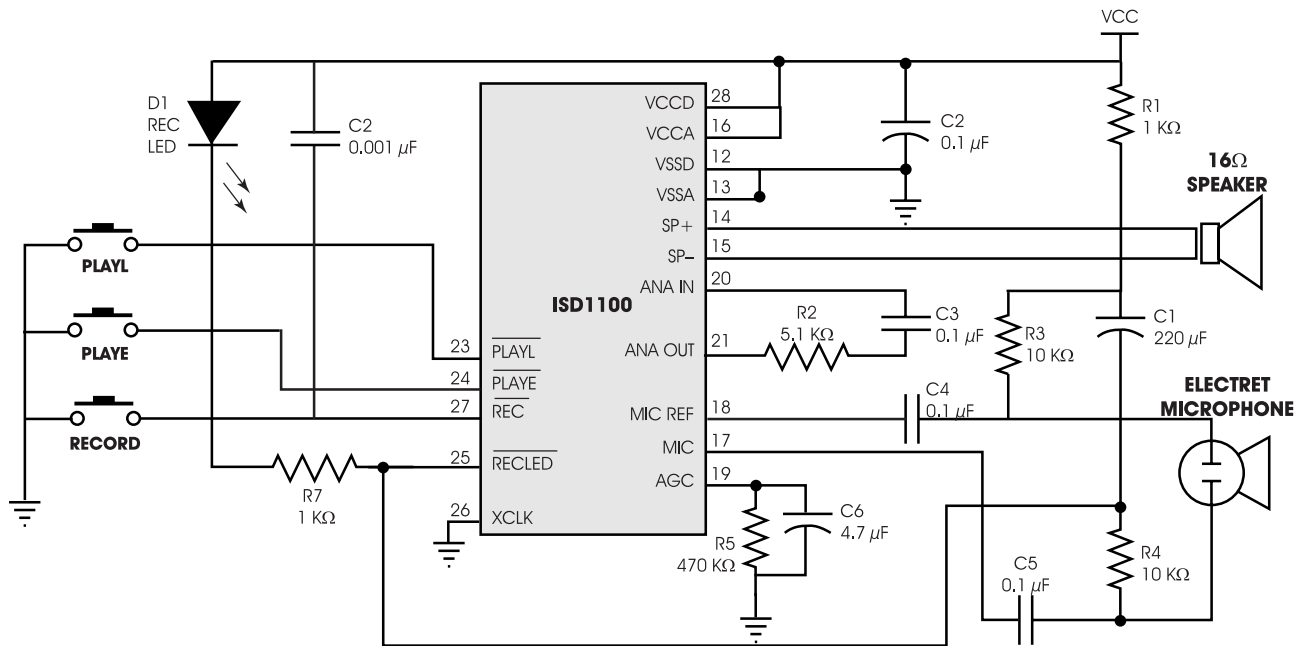


Figure 4: Application Example



FUNCTIONAL DESCRIPTION EXAMPLE

The following example operating sequence demonstrates the functionality of the ISD1100 series devices.

1. Record a message filling the memory.

Pulling the $\overline{\text{REC}}$ signal LOW initiates a record cycle from the beginning of the message space. If $\overline{\text{REC}}$ is held LOW, the recording continues until the message space has been filled. Once the message space is filled, recording ceases. The device will automatically power down after $\overline{\text{REC}}$ is released HIGH. An EOM marker is written at the end of memory.

2. Edge-activated playback.

Pulling the $\overline{\text{PLAYE}}$ signal LOW initiates a playback cycle from the beginning of the message space. The rising edge of $\overline{\text{PLAYE}}$ has no effect on operation. If a recording has filled the message space, the entire message is played. When the device

reaches the EOM marker, it automatically powers down. A subsequent falling edge on $\overline{\text{PLAYE}}$ initiates a new play cycle from the beginning of the memory.

3. Level-activated playback.

Pulling the $\overline{\text{PLAYL}}$ signal LOW initiates a playback cycle from the beginning of the message space. If recording has filled the message space, the entire message is played. When the device reaches the EOM marker, it automatically powers down. A subsequent falling edge on $\overline{\text{PLAYL}}$ initiates a new play cycle from the starting address.

4. Level-activated playback (truncated).

If $\overline{\text{PLAYL}}$ is pulled HIGH any time during the playback cycle, the device stops playing and enters the power-down mode. A subsequent falling edge on $\overline{\text{PLAYL}}$ initiates a new play cycle from the beginning of memory.

5. Record (interrupting playback).

The $\overline{\text{REC}}$ signal takes precedence over other operations. Any LOW-going transition on $\overline{\text{REC}}$ initiates a new record operation from the beginning of the memory, regardless of any current operation in progress.

6. Record a message, partially filling the memory.

A record operation need not fill the entire memory. Releasing the $\overline{\text{REC}}$ signal HIGH before filling the message space causes the recording to stop and an EOM marker to be placed. The device powers down automatically.

7. Play back a message that partially fills the memory.

Pulling the $\overline{\text{PLAYE}}$ or $\overline{\text{PLAYL}}$ signal LOW initiates a playback cycle which is then completed when the EOM marker is encountered. Playback ceases and the device powers down.

8. $\overline{\text{RECLED}}$ operation.

The $\overline{\text{RECLED}}$ output pin provides an active-LOW signal which can be used to drive an LED as a "record-in-progress" indicator. It returns to a HIGH state when the $\overline{\text{REC}}$ pin is released HIGH or when the recording is completed due to the memory being filled. This pin also pulses LOW to indicate an EOM at the end of a message being played.

APPLICATIONS NOTE

Some users may experience an unexpected recording taking place when their circuit is powered up, or the batteries are changed, and V_{CC} rises faster than $\overline{\text{REC}}$. This undesired recording prevents playback of the previously recorded message. A spurious EOM marker may appear at the very beginning of the memory, preventing access to the original message, and nothing is played.

To prevent this occurrence, place a capacitor (approximately, 0.001 μF) between the control pin, $\overline{\text{REC}}$, and V_{CC} . This pulls the control pin voltage up with V_{CC} as it rises. Once the voltage is HIGH, the pull-up device will keep the pin HIGH until intentionally pulled LOW, preventing the false EOM marker.

Since this condition is dependent upon factors such as the capacitance of the user's printed circuit board, not all circuit designs will exhibit the spurious marker. It is recommended, however, that the capacitor is included for design reliability. A more detailed explanation and resolution of this occurrence is described in Application Information.

ISD1100 SERIES PHYSICAL DIMENSIONS

Figure 5: 28-Lead 0.600-Inch Plastic Dual Inline Package (PDIP) (P)

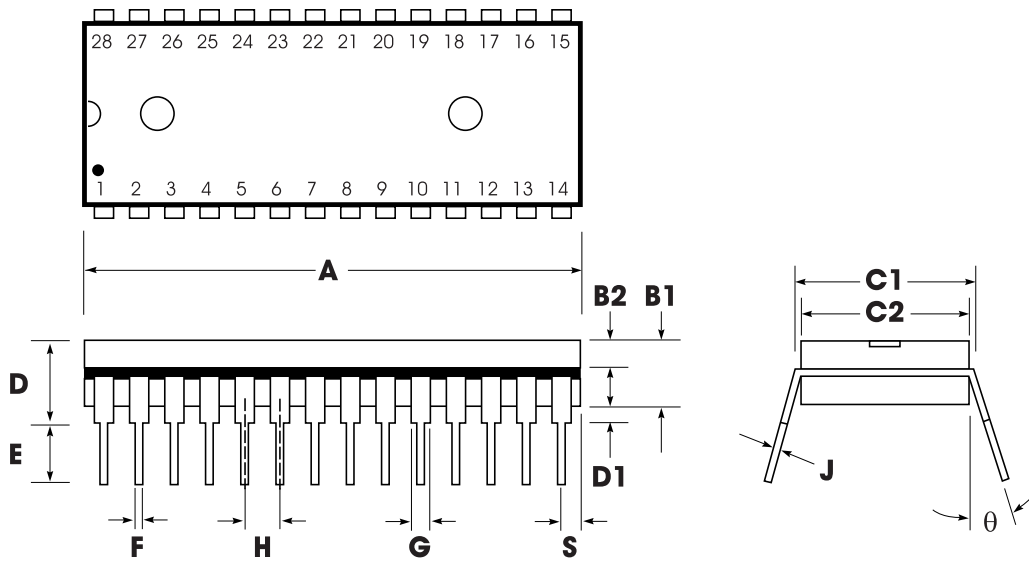


Table 11: Plastic Dual Inline Package (PDIP) (P) Dimensions

	INCHES			MILLIMETERS		
	Min	Nom	Max	Min	Nom	Max
A	1.445	1.450	1.455	36.70	36.83	36.96
B1		0.150			3.81	
B2	0.065	0.070	0.075	1.65	1.78	1.91
C1	0.600		0.625	15.24		15.88
C2	0.530	0.540	0.550	13.46	13.72	13.97
D			0.19			4.83
D1	0.015			0.38		
E	0.125		0.135	3.18		3.43
F	0.015	0.018	0.022	0.38	0.46	0.56
G	0.055	0.060	0.065	1.40	1.52	1.65
H		0.100			2.54	
J	0.008	0.010	0.012	0.20	0.25	0.30
S	0.070	0.075	0.080	1.78	1.91	2.03
q	0°		15°	0°		15°

NOTE: Lead coplanarity to be within 0.005 inches.

Figure 6: 28-Lead 0.300-Inch Plastic Small OutLine Integrated Circuit (SOIC) (S)

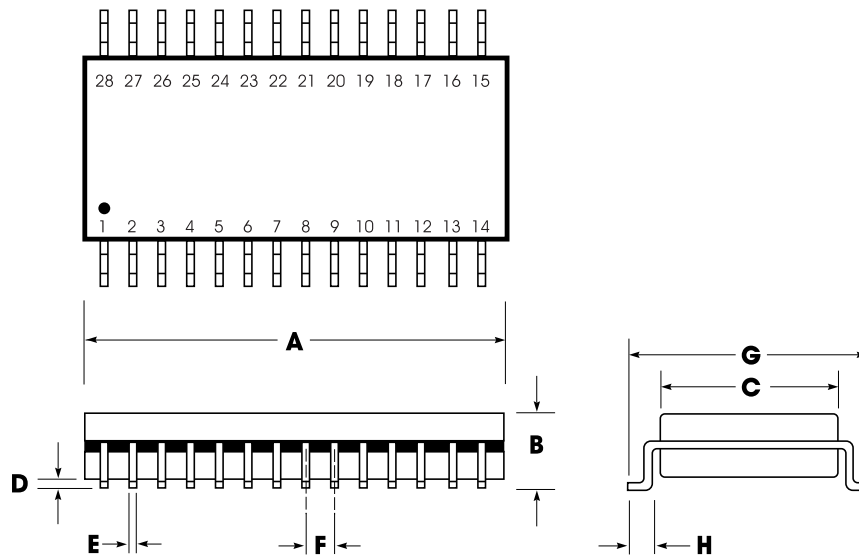


Table 12: Plastic Small OutLine Integrated Circuit (SOIC) (S) Dimensions

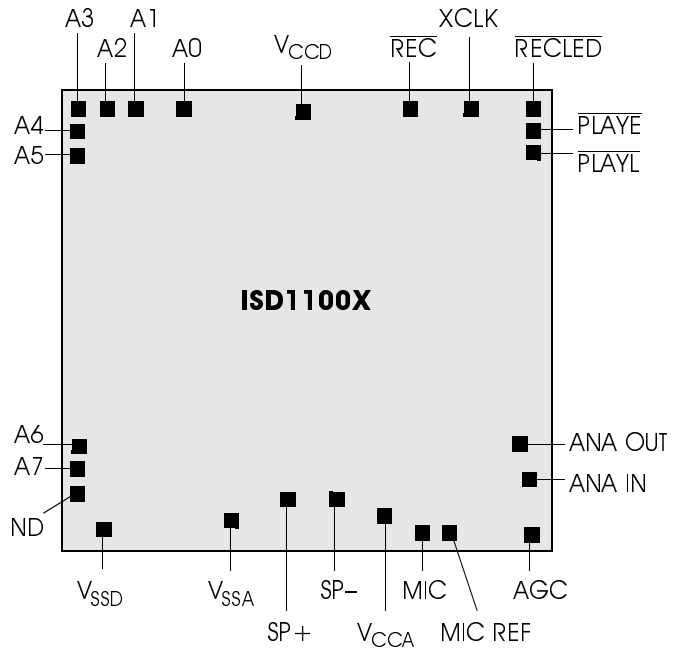
	INCHES			MILLIMETERS ^p		
	Min	Nom	Max	Min	Nom	Max
A	0.701	0.706	0.711	17.81	17.93	18.06
B	0.097	0.101	0.104	2.46	2.56	2.64
C	0.292	0.296	0.299	7.42	7.52	7.59
D	0.005	0.009	0.0115	0.127	0.22	0.29
E	0.014	0.016	0.019	0.35	0.41	0.48
F		0.050			1.27	
G	0.400	0.406	0.410	10.16	10.31	10.41
H	0.024	0.032	0.040	0.61	0.81	1.02

NOTE: Lead coplanarity to be within 0.004 inches.

Figure 7: ISD1100 Series Bonding Physical Layout¹

ISD1100X

- I. Die Dimensions
X: 172.2 ± 1 mils
Y: 138.2 ± 1 mils
- I. Die Thickness⁽²⁾
17.5 ± 1 mils
- I. Pad Opening
88 x 112 microns
3.46 x 4.41 mils



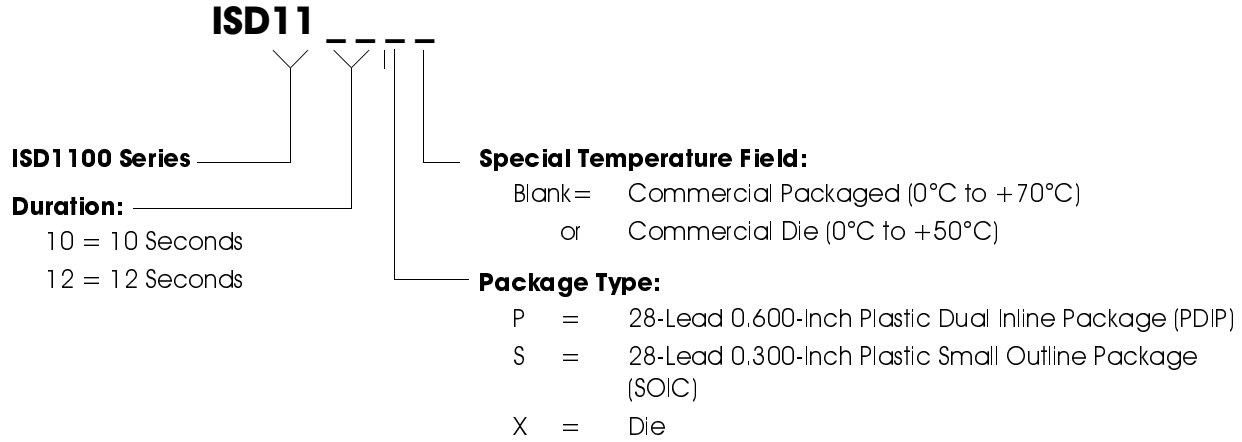
1. The backside of die is internally connected to V_{SS} . It **MUST NOT** be connected to any other potential or damage may occur.
2. Die thickness is subject to change, please contact ISD factory for status.

Table 13: ISD1100 Series PIN/PAD Designations, with Respect to Die Center (μm)

Pin	Pin Name	X Axis	Y Axis
A0	Address 0	-1364.0	1589.6
A1	Address 1	-1648.4	1589.6
A2	Address 2	-1816.4	1589.6
A3	Address 3	-2013.6	1515.6
A4	Address 4	-2013.6	1337.6
A5	Address 5	-2013.6	1129.6
A6	Address 6	-2013.6	-831.2
A7	Address 7	-2013.6	-1022.0
NC	No Connect	-2013.6	-1361.6
V _{SSD}	V _{SS} Digital Power Supply	-1893.6	-1588.0
V _{SSA}	V _{SS} Analog Power Supply	-357.6	-1588.0
SP+	Speaker Output +	-17.2	-1512.8
SP-	Speaker Output -	412.4	-1512.8
V _{CCA}	V _{CC} Analog Power Supply	780.0	-1552.4
MIC	Microphone Input	992.0	-1590.0
MIC REF	Microphone Reference	1169.2	-1590.0
AGC	Automatic Gain Control	1978.4	-1590.0
ANA IN	Analog Input	2005.6	-1196.4
ANA OUT	Analog Output	1991.2	-995.2
PLAY \bar{L}	Level-Activated Playback	2014.4	1224.4
PLAYE	Edge-Activated Playback	2014.4	1392.8
RECLED \bar{D}	Record LED Output	2012.4	1587.6
XCLK	No Connect (optional)	1581.2	1589.6
REC \bar{C}	Record	752.8	1589.6
V _{CCD}	V _{CC} Digital Power Supply	-48.0	1545.2

ORDERING INFORMATION

Product Number Descriptor Key



When ordering ISD1100 series devices, please refer to the following valid part numbers.

Part Number	Part Number
ISD1110P	ISD1112P
ISD1110X	ISD1112X
ISD1110S	ISD1112S

For the latest product information, access ISD's worldwide website at <http://www.isd.com>.